

CLAIMS

1. A capsule type curing agent which comprises a core comprising an amine type curing agent (A) and a capsule and a membrane covering said core, wherein said capsule membrane has a bonding group (x) absorbing infrared ray of a wave-number of 1630 to 1680 cm^{-1} and/or a bonding group (y) absorbing infrared ray of a wave-number of 1680 to 1725 cm^{-1} , and contains cured material of an epoxy resin by the amine type curing agent (A) as a curing agent, and weight ratio of the core and the capsule membrane is $100:1$ to $100:100$.
2. The capsule type curing agent according to Claim 1, wherein in ^{13}C -NMR spectrum of the capsule membrane, ratio of a largest peak height between 37 to 47 ppm to a largest peak height between 47 to 57 is not lower than 3 .
3. The capsule type curing agent according to Claim 1 or 2, wherein melt viscosity of the amine type curing agent (A) at 160°C is not higher than $10\text{ Pa}\cdot\text{s}$.
4. The capsule type curing agent according to any one of Claims 1 to 3, wherein the amine type curing agent (A) has at least one tertiary amino group in one molecule thereof.
5. The capsule type curing agent according to any one of Claims 1 to 4, wherein total amount of chlorines in the amine type curing agent (A) is not more than 400 ppm .
6. The capsule type curing agent according to

any one of Claims 1 to 5, wherein the amine type curing agent (A) is a reaction product between an epoxy resin (B) having total amount of chlorines of not more than 400 ppm and an amine compound (C).

7. The capsule type curing agent according to any one of Claims 1 to 6, wherein total amount of chlorines in an epoxy resin (D) is not more than 400 ppm.

8. The capsule type curing agent according to any one of Claims 1 to 7, wherein the capsule membrane is comprised of a shell of a reaction product between the amine type curing agent (A) and the epoxy resin (D) and an intermediate layer having the bonding group (x) and/or the bonding group (y).

9. A masterbatch type curing agent comprising 100 parts by weight of the capsule type curing agent according to any one of Claims 1 to 8 and 10 to 50,000 parts by weight of an epoxy resin (E).

10. An epoxy resin composition comprising, as main components, 100 parts by weight of an epoxy resin (F) and the capsule type curing agent according to any one of Claims 1 to 8 or the masterbatch type curing agent according to Claim 9 or a mixture thereof in such an amount as the total amount of the capsule type curing agents is 0.1 to 100 parts by weight.

11. An epoxy resin composition comprising, as main components, 100 parts by weight of the epoxy resin (F), 1 to 200 parts by weight of at least one kind of a

curing agent (G) selected from the group consisting of acid anhydrides, phenols, hydrazides and guanidines, and the capsule type curing agent according to any one of Claims 1 to 8 or the masterbatch type curing agent according to Claim 9 or a mixture thereof in such an amount as the total amount of the capsule type curing agent is 0.1 to 100 parts by weight.

12. An anisotropic conductive material containing the epoxy resin composition according to Claim 10 or 11.

13. A conductive adhesive material containing the epoxy resin composition according to Claim 10 or 11.

14. An insulating adhesive material containing the epoxy resin composition according to Claim 10 or 11.

15. An encapsulant containing the epoxy resin composition according to Claim 10 or 11.